

## COPY OF PAPERS ORIGINALLY FILED IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:

Charles W.C. Lin

Title:

SUPPORT CIRCUIT WITH A TAPERED THROUGH-HOLE

FOR A SEMICONDUCTOR CHIP ASSEMBLY

Serial No.:

10/002,732

Filed:

November 15, 2001

Examiner:

Unknown

**Group Art Unit:** 

Unknown

Atty. Docket No.:

P012-1

ASSISTANT COMMISSIONER FOR PATENTS Washington, D.C. 20231

TRANSMITTAL OF FORMAL DRAWINGS

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Attached please find the formal drawings (17 sheets) for this application.

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on December 17, 2001.

David M. Signond

Attorney for Applicant

19,17,61

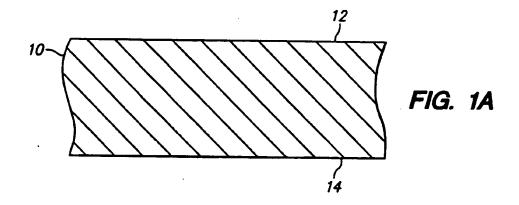
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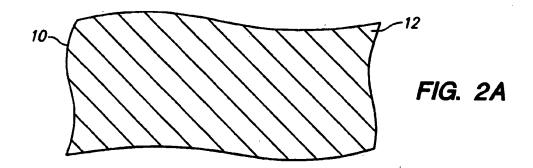
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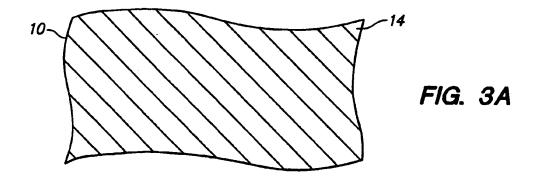
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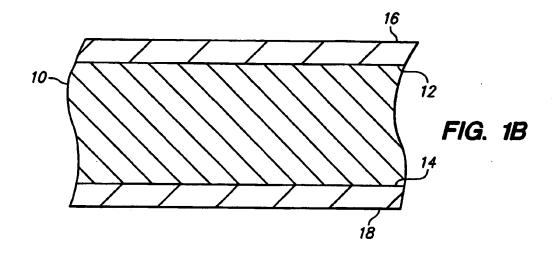
David M. Sigmond Attorney for Applicant

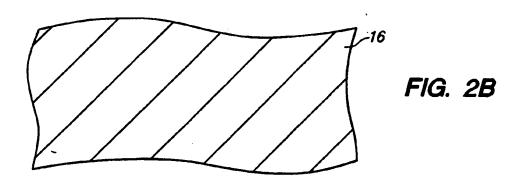
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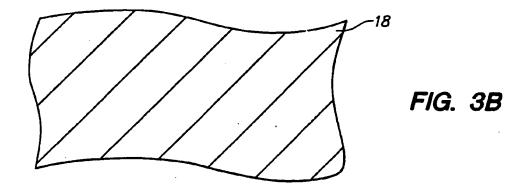


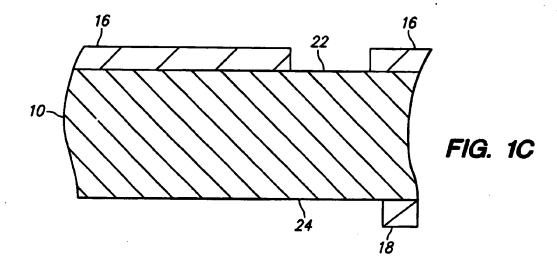


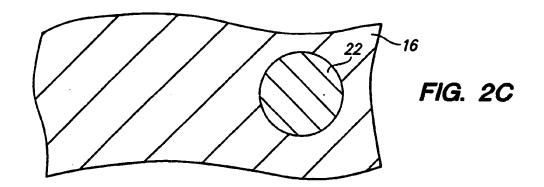


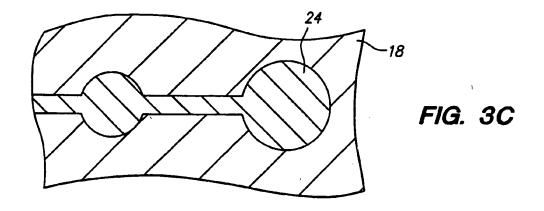


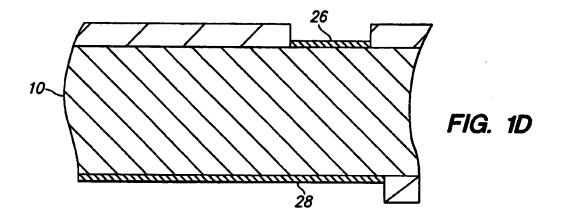


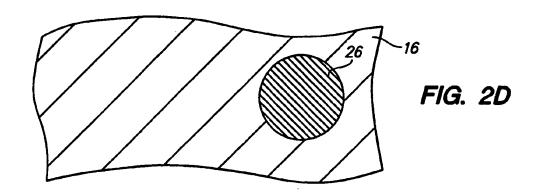


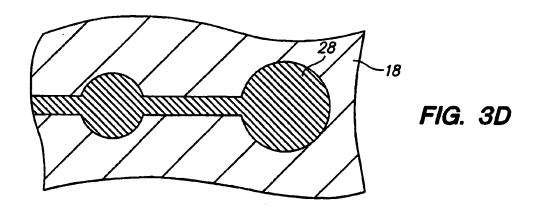


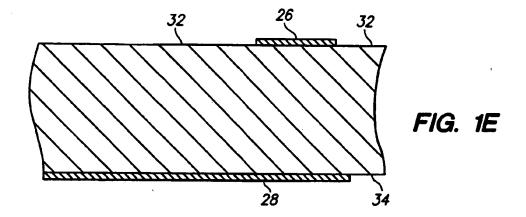


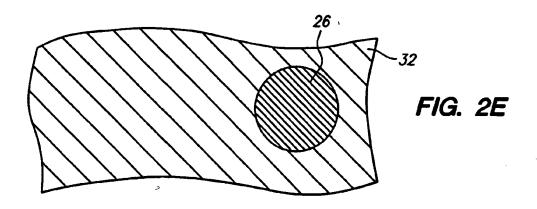


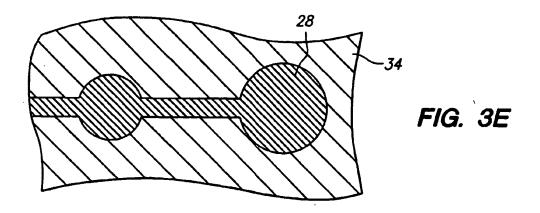


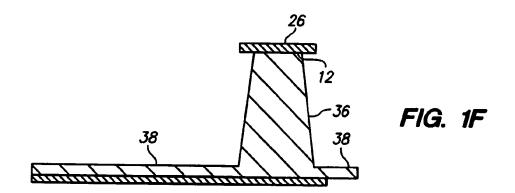


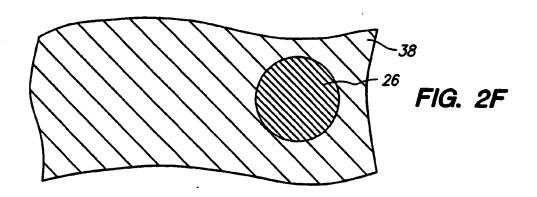


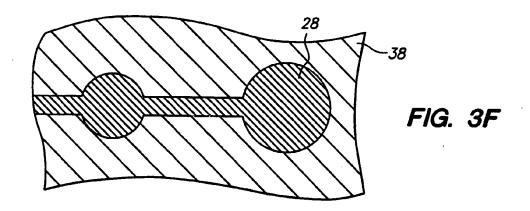


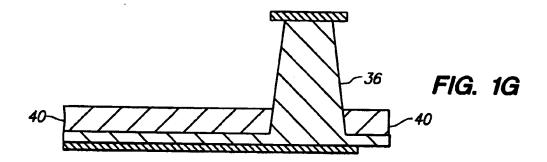


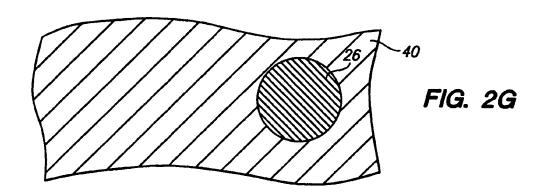


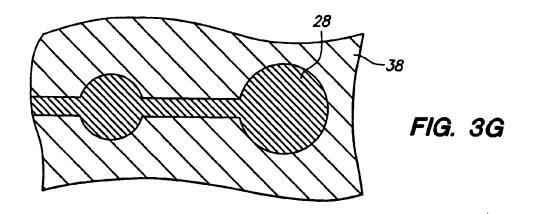


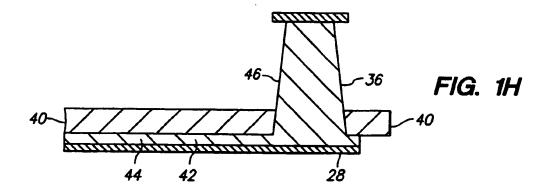


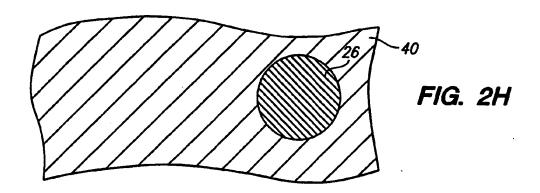


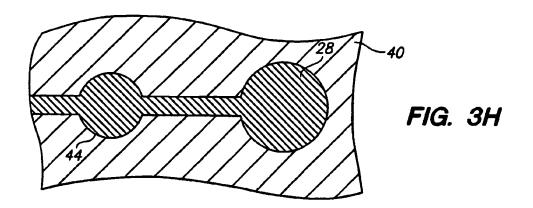


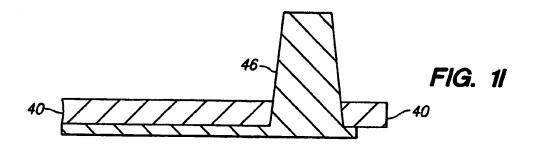


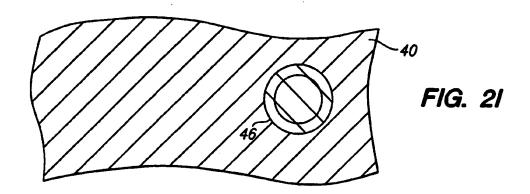


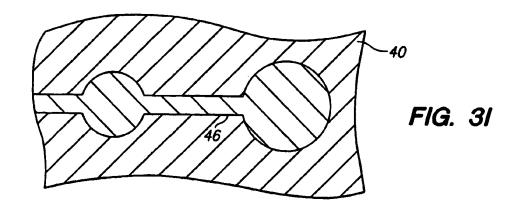


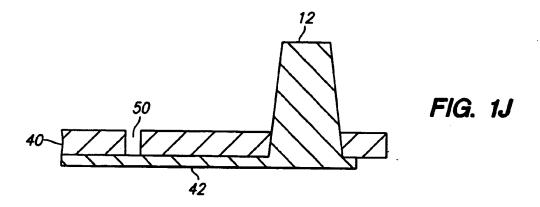


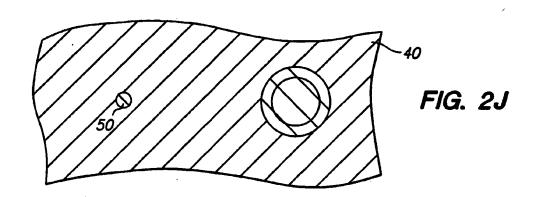


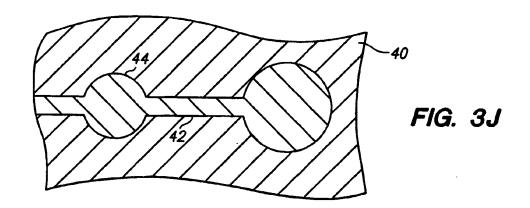


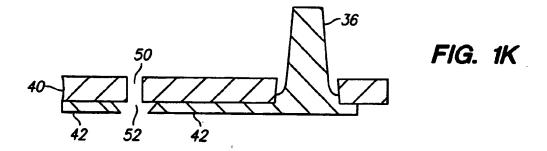


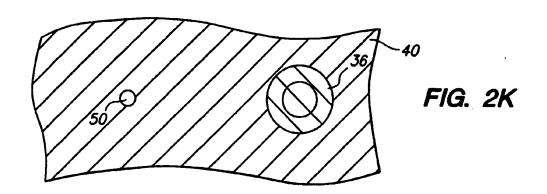


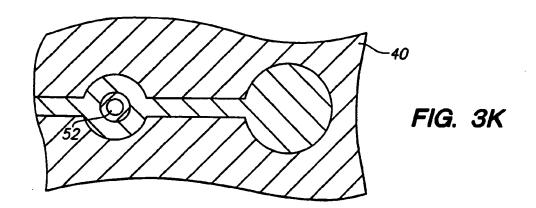


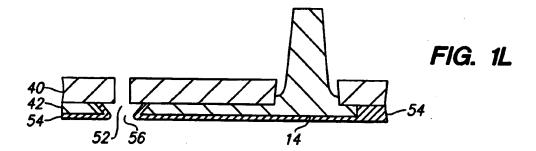


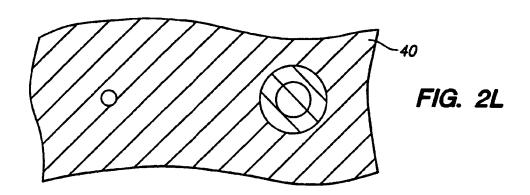


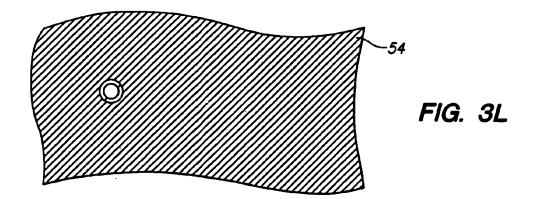


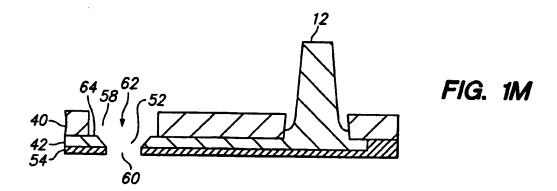


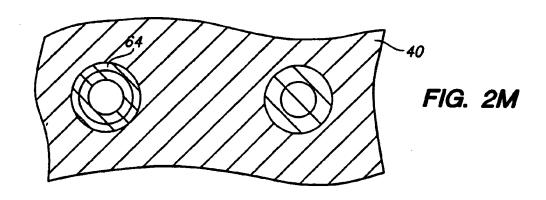


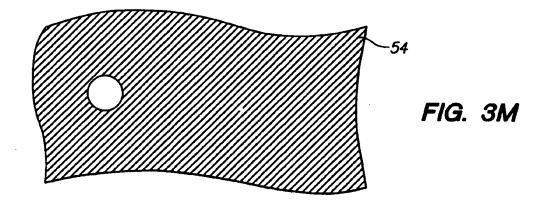


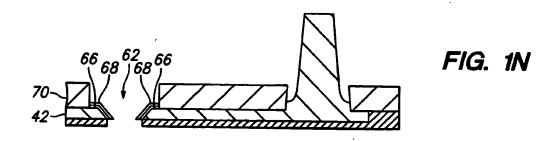












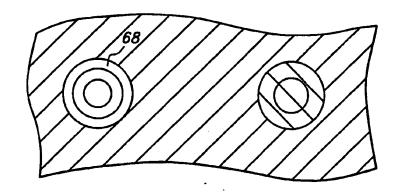


FIG. 2N

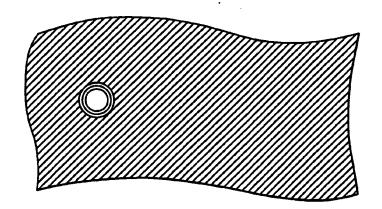
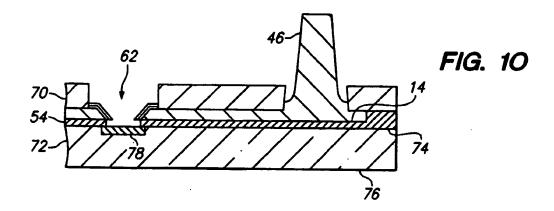
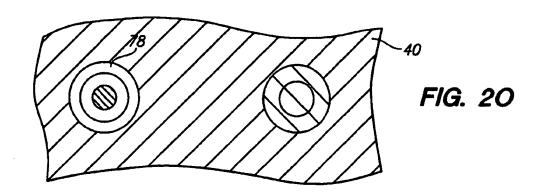
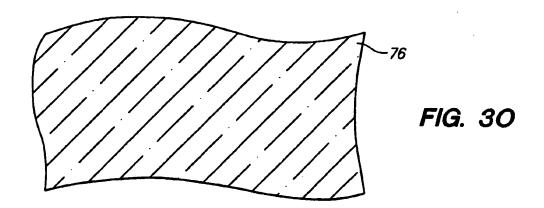


FIG. 3N







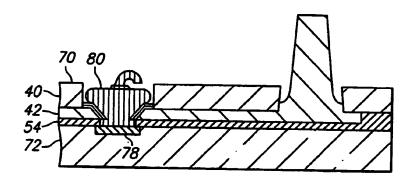


FIG. 1P

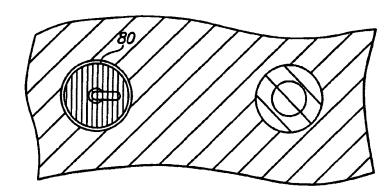


FIG. 2P

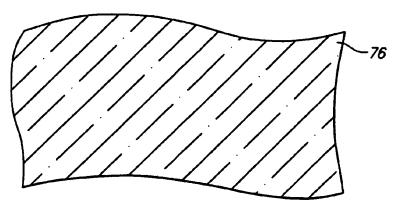


FIG. 3P

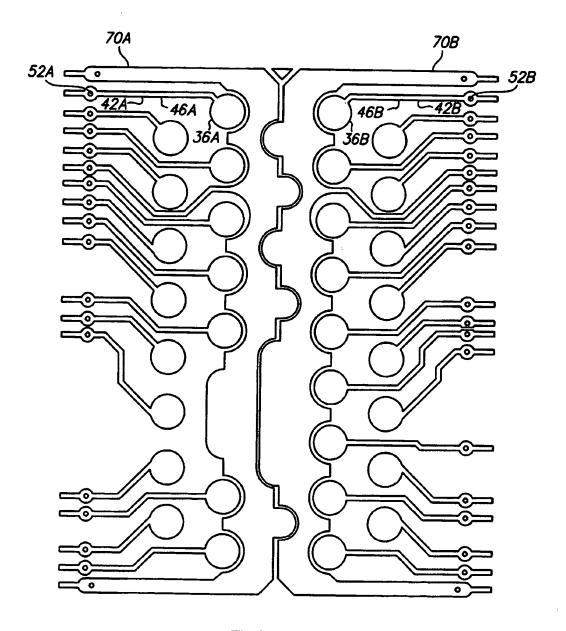


FIG. 4